

Effects of local grain misorientation and β -Sn elastic anisotropy on whisker and hillock formation – CORRIGENDUM

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In Sarabol et al.,¹ Fig. 1 is missing the following permission line:

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The authors regret the mistake.

REFERENCE

1. Pylin Sarabol, Wei-Hsun Chen, Aaron E. Pedigo, Peng Su, John E. Blendell, and Carol A. Handwerker: Effects of local grain misorientation and β -Sn elastic anisotropy on whisker and hillock formation. *J. Mater. Res.* (2013).